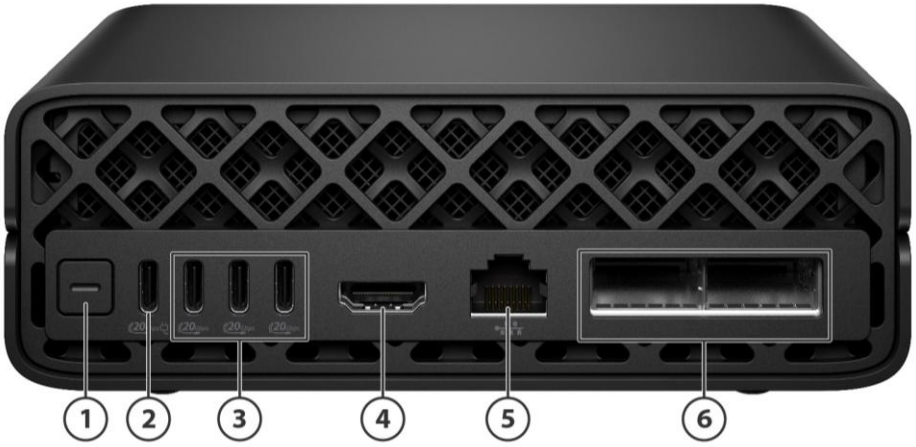
Overview

HP ZGX Nano G1n AI Station



Front View



Rear View

1. Power button
2. 1x USB Type-C (USB-C) power connector (240W)
3. 3x USB 3.2 Type-C (USB-C) 20Gbps (supports Alt mode DisplayPort 1.4a; total output power 30W)
4. 1x HDMI 2.1a
5. 1x RJ-45 (10GbE LAN)
6. 2x QSFP (200GbE LAN); Left port (Port0); Right port (Port1)

Overview

OVERVIEW

Form Factor	Mini
Operating System	NVIDIA DGX™ OS 7 / Ubuntu 24.04 **NOTE:** This product does not support Microsoft Windows.
Color	Black
Processor	NVIDIA GB10 Grace Blackwell Superchip Blackwell Architecture GPU 20 core Arm, 10 Cortex-X925 + 10 Cortex-A725 CPU 16MB L2 Cache Blackwell Generation CUDA Cores 5th Generation Tensor Cores 4th Generation RT Cores 1x NVEC 1x NVDEC 1x 64GB LPDDR5x, coherent unified system memory, 16 channel channels, soldered-down
Memory	128GB LPDDR5x, coherent unified system memory, 16 channels, soldered-down
Memory Bandwidth	273 GB/s
Internal I/O	Internal Slot M.2-M: 1 PCIe Gen5 x4
Rear I/O	1x USB Type-C (USB-C) power connector (240W); 3x USB 3.2 Type-C (USB-C) 20Gbps (total output power 30W); 1x HDMI 2.1a; 1x RJ-45 (10GbE LAN); 2x QSFP (200GbE LAN)
Chassis Dimensions (H x W x D)	H (without feet): 2.01” (5.1cm) H (with feet): 2.1" (5.45cm) W: 5.9" (15cm) D: 5.9" (15cm) (Standard desktop orientation)
Packaged Dimensions (H x W x D)	L: 8.5" (21.6cm) W: 5.6" (14.2cm) H: 10.7" (27.2cm)
Rack Dimensions	**NOTE:** This product is neither supported nor qualified for rack mounting.
Weight	Exact weights depend upon configuration (System weight only). Starting at 1.25kg (2.76lbs.) Exact weights depend upon configuration (Packaged weight). Starting at 2.5kg (5.4lbs.)
Power Adapter	240W external USB Type-C power adapter, 89% efficiency, active PFC **NOTE:** For optimal performance and reliable operation, use only the power adapter supplied with the ZGX Nano system. Use of third-party or non-supplied adapters may result in degraded performance, boot failure, or unexpected system shutdowns. **NOTE:** This product does not include a keyboard or mouse.

System Technical Specifications

PROCESSORS

	Factory Configured	Option Kit
NVIDIA Grace Blackwell		
NVIDIA GB10 Grace Blackwell Superchip	Y	N

PCIe SOLID STATE DRIVES

	Factory Configured	Option Kit
HP 2TB PCIe-4x4 2242 NVMe SED OPAL Value TLC M.2 SSD		
HP 4TB PCIe-4x4 2242 NVMe SED OPAL Value TLC M.2 SSD	Y	N

MEMORY

	Factory Configured	Option Kit
64GB LPDDR5x coherent unified system memory	Y	N
128GB LPDDR5x coherent unified system memory	Y	N

NETWORKING AND COMMUNICATIONS

	Factory Configured	Option Kit	Option Kit Part Number
HP ZGX 0.4m QSFP112 Ethernet DAC Cable	Y	Y	C20MQAA

KEUBOARD/MOUSE

	Factory Configured	Option Kit	Option Kit Part Number
HP 425 Programmable Bluetooth Wireless Mouse	N	Y	7M1D5AA
HP 695 Qi-Charging Bluetooth Wireless Mouse	N	Y	8F1Y4AA
HP 705 Rechargeable Wireless Mouse	N	Y	AZ7B1AA
HP 720 Multi-Device Rechargeable Wireless Keyboard and Mouse Combo	N	Y	9T5A9AA
HP 725 Multi-Device Rechargeable Wireless Keyboard	N	Y	9T5B2AA
HP 925 Ergonomic Vertical Bluetooth 5.0 + Wireless 2.4GHz Wireless Mouse	N	Y	6H1A5AA
HP Multi-Device Dual-Mode Keyboard 495K	N	Y	BD5F5AA

POWER

	Factory Configured	Option Kit	Option Kit Part Number
HP ZGX 240W USB-C AC Adapter	Y	Y	CM5A0AA

INPUT/OUTPUT ADAPTERS

	Factory Configured	Option Kit	Option Kit Part Number
HP USB-C to USB 3.0 Adapter	N	Y	N2Z63AA
HP USB-C to USB-A Hub	N	Y	Z6A00AA

OPERATING SYSTEMS

NVIDIA DGX™ OS 7 / Ubuntu 24.04

NOTE: This product does not support Microsoft Windows.

SOFTWARE COMPONENTS AND APPLICATIONS

Preinstalled with NVIDIA DGX OS

- NVIDIA Connect
- CUDA 13
- NVIDIA RTX Driver 580
- DGX Dashboard
- NVIDIA AI Workbench

Ready to build?
Install the ZGX Toolkit from hp.com/zgx-onboard to start prototyping and fine-tuning LLM models in minutes.

System Technical Specifications

SYSTEM BOARD

System Board Form Factor		140mm X 122.455 mm
Processor		2970 Ball BGA
Embedded Controller		Microchip
Memory Type Supported		LPDDR5x, coherent unified system memory,16 channels, soldered-down
Memory Speed Supported		8533 MHz
Memory Bandwidth		273 GB/s
Maximum Memory		128GB
Memory Configuration (Supported)		64GB 128GB
Supported Interfaces	**Integrated Graphics**	NVIDIA Blackwell Architecture (GB10) 1x HDMI 2.1a port • Maximum resolution, single display: 8K (7680 x 4320) at 30 Hz 3x USB 3.2 Type-C (USB-C) 20Gbps ports; supports Alt mode DisplayPort 1.4a • Maximum resolution, single display: 8K (7680 x 4320) at 60 Hz **NOTE:** For 8K (7860 × 4320) resolutions, displays should be connected using direct cables. Using adapters, a hub, or a dock may lead to inconsistent performance or degraded video output. **NOTE:** For optimal compatibility and performance, users should connect displays via HDMI or USB Type-C ports. Users may experience limited compatibility or functionality when connecting displays through Thunderbolt ports.
	Network Controller	Realtek RTL8127-CG 10GbE Ethernet Controller NVIDIA Mellanox ConnectX-7 200GbE Ethernet Controller
	WLAN and Bluetooth®	AzureWave AW-EM637 IEEE 802.11 a/b/g/n/ac/ax/be Wireless LAN 2T2R and Bluetooth 5.4 Combo Module **NOTE:** Available in certain countries without WLAN and Bluetooth Module. Contact your nearest HP sales office.
USB Connector(s)	**Rear**	1x USB Type-C power connector (240W); 3x USB 3.2 Type-C (USB-C) 20Gbps (supports Alt mode DisplayPort 1.4a; total output power 30W)

System Technical Specifications

Integrated Audio	Yes
Display Connectors	HDMI 2.1a
Flash ROM	Yes
System Fan Header	Yes
Front PCI Fan Header	None
Front Control Panel/Speaker Header	None
CMOS Battery Holder – Lithium	Y
Integrated Trusted Platform Module	Integrated TPM 2.0 Convertible to FIPS 140-2 Certified mode The TPM module disabled where restricted by law
Keyboard/Mouse	This product does not include a keyboard or mouse.
Power Supply	240W external USB Type-C power adapter, 89% efficiency, active PFC **NOTE:** For optimal performance and reliable operation, use only the power adapter supplied with the ZGX Nano system. Use of third-party or non-supplied adapters may result in degraded performance, boot failure, or unexpected system shutdowns.

System Configurations

HP ZGX Nano G1n Configuration #1

Processor	NVIDIA GB10 Grace Blackwell Superchip
Memory	128GB LPDDR5x, coherent unified system memory
Graphics	Integrated Graphics
Disks/Optical/Floppy	1x 1TB PCIe 2242 Val M.2 SSD
Power Supply	240W external USB Type-C power adapter, 89% efficiency, active PFC

Energy Consumption	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	37.810	36.740	37.890
Normal Operation (Long idle)	36.630	35.510	36.830
Normal Operation (Busy Max)	226.270	223.810	228.580
Sleep	36.630	35.510	36.830
Off	1.340	1.280	1.350

Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	129.280	125.621	129.553
Normal Operation (Long idle)	125.245	121.416	125.929
Normal Operation (Busy Max)	773.662	765.251	781.561
Sleep	125.245	121.416	125.929
Off	4.582	4.377	4.616

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

HP ZGX Nano G1n Configuration #2

Processor	NVIDIA GB10 Grace Blackwell Superchip
Memory	128GB LPDDR5x, coherent unified system memory
Graphics	Integrated Graphics
Disks/Optical/Floppy	1x 4TB PCIe 2242 Val M.2 SSD
Power Supply	240W external USB Type-C power adapter, 89% efficiency, active PFC

Energy Consumption	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	37.860	36.780	37.950
Normal Operation (Long idle)	36.710	35.520	36.850
Normal Operation (Busy Max)	227.840	223.960	228.310
Sleep	36.710	35.520	36.850
Off	1.340	1.280	1.350

Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	129.451	125.758	129.759
Normal Operation (Long idle)	125.519	121.450	125.998
Normal Operation (Busy Max)	779.031	765.764	780.638
Sleep	125.519	121.450	125.998
Off	4.582	4.377	4.616

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	**Sound Power (L_{WAd}, bels)**	**Sound Pressure (L_{pAm}, decibels)**
Idle	3.4	22.0
Fixed Disk – Random writes	3.9	27.6

System Technical Specifications

Operating Voltage Range		90-264 VAC
Rated Voltage Range		100-120 VAC 200-240 VAC
Rated Line Frequency		50-60 Hz
Operating Line Frequency Range		47-63 Hz
Rated Input Current		100-120 VAC; 3.1A 200-240 VAC; 1.56A
Environmental Requirements	**Temperature**	Operating: 5° to 30° C (40° to 86° F) Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation Non-operating: -30° to 60° C (-22° to 140° F) Maximum rate of change: 10°C/hr
	Humidity	Operating: 8% to 85% RH, non- condensing, 35° C maximum wet bulb Non-operating: 8% to 90% RH, non-condensing, 35° C maximum wet bulb

PHYSICAL SECURITY AND SERVICEABILITY

Access Panel	#1 Phillips screwdriver is needed for top and bottom panel
Memory	Soldered Down
System Board	Screw-In
CPUs and Heatsinks	#1 Phillips screwdriver is needed to remove the heatsink
Rear Power Button	Yes
Front Power LED	Yes, green (system powered on)
System/Emergency ROM Flash Recovery	Recovers corrupted system BIOS.
Cooling Solution	Air cooled forced convection
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI). • Allows the system to wake from a low power mode. • Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
Flash ROM	Yes
CMOS Battery Holder	Yes

BIOS

BIOS 64-bit Services	BIOS supports 64-bit Operating systems.
PCI 4.0 Support	Full BIOS support for PCI Express through industry standard interfaces.
ROM Based Computer Setup Utility (F10)	AMI standard BIOS setup
Boot Control	Disables the ability to boot from removable media on supported devices.
Ownership Tag	None
Remote Wakeup/Remote Shutdown	None
Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)	Allows a new or existing system to boot over the network and download software, including the operating system.
ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility. Version is available through an industry standard interface so that management SW applications can use and report this information.
Keyboard-less Operation	The system can be booted without a keyboard.
Asset Tag	The user or MIS to set a unique tag string in non-volatile memory.
UEFI Specification Revision	2.8
ACPI	Advanced Configuration and Power Management Interface, Version 6.0
xHCI	eXtensible Host Controller Interface for Universal Serial Bus, Revision 1.2
PCI	PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7
PCI Express	PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 4.0
TPM	Trusted Computing Group TPM Specification Version 2.0 Common Criteria EAL4+ certified. FIPS 140-2 Certification TCG TPM Certified products list: http://www.trustedcomputinggroup.org/certification/tpm-certified-products/
USB	Universal Serial Bus Revision 1.1 Specification Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.2 Specification Universal Serial Bus Revision 4.0 Specification
SMBIOS	System Management BIOS Reference Specification, Version 3.4 External BIOS simulator found at: http://csrsml.itcs.hp.com/

WARRANTY

HP Customer Support: One-year hardware limited warranty in most regions; Optional HP Care Packs[1] are available and are extended service contracts that go beyond your standard limited warranties; for more details visit http://www.hp.com/go/cpc

[1]HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

For current drivers, firmware, BIOS, utilities, and documentation, including Customer Advisories, security bulletins, and release notes, visit www.hp.com/support and enter the product name. Availability of updates may vary by configuration and region; HP recommends routinely checking the Support site for the latest advisories and releases.

Certification and Compliance

Environmental Sustainability questions concerning:

- Ecolabels
- California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uk-en/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpuk-mu_chev/certificates)
- GS Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- CCC Certificates
- Ergonomics

Please contact techregshelp@hp.com

NOTE: The product description/product type/product category for Certifications may be described as any of the following: AI Station/Small Scale Server/Workstation.
Product is TAA Compliant.

SOCIAL AND ENVIRONMETAL RESPONSIBILITY

Eco-Label Certifications & This product has received or is in the process of being certified to the following approvals and may be

System Technical Specifications

declarations

labeled with one or more of these marks:

- IT ECO declaration
- California Energy Commission (CEC) – Small Scale Servers
- Japan PC Green label*
- Japan Top Runner
- Australia and New Zealand MEPS

Sustainable Impact Specifications

- Product Carbon Footprint
- At least 25% ITE-Derived closed loop plastic[1]
- 40% post-consumer recycled plastic[1]
- 20% recycled steel[2]
- 75% recycled aluminum[2]

100% of HP paper-based packaging is from recycled or certified sustainable sources[3]

Longevity and Upgrading

This product cannot be upgraded.

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the Gold level, see http://www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 96.8% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Corrugated	327 g
Internal:	PLASTIC/Polyethylene low density – LDPE	6 g

The plastic packaging material contains at least 30% recycled content.

The corrugated paper packaging materials contains at least 93.0% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c05998906):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

System Technical Specifications

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to:
https://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c05403198
or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: HP Product Disassembly Instruction Website. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

- Sustainable Impact Report
  - https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06040843
- Eco-label certifications
  - https://www.hp.com/us-en/sustainable-impact/document-reports.html#filters_documents_reports-=document_type-type_energy_star,type_epeat,type_tcoISO
- ISO 14001 certificates
  - https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c04777932

Footnotes

1. Recycled plastic is expressed as a percentage of the total weight plastic. Post-consumer recycled is based on the definition set in the EPEAT standard for computers, IEEE 1680.1-2018 standard.
2. Recycled metal is expressed as a percentage of the total weight of the metal according to ISO 14021 definitions for metal parts over 25 grams.
3. HP paper and fiber-based packaging for PCs, displays, home and office print, and supplies is reported by suppliers as recycled or certified, with a minimum of 97% by volume verified by HP. Packaging is the box that comes with the product and all paper-based materials inside the box. Packaging for personal systems accessories and spare parts is not included. Plastic cushions are made from >90% recycled plastic.

Technical Specifications - Storage Drives

STORAGE

PCIe SSDs for HP ZGX Nano G1n AI Station

HP M.2 2242 PCIE-4X4 1TB SED Value TLC PCIe SSD

Capacity	1TB
Protocol	PCIe
Form Factor	M.2 in native slot on motherboard
Controller	NVMe
NAND Type	3D TLC
Endurance	600TBW (TB Written)
Reliability	1.5M Hours
Interface	PCI Express 4.0 x4 electrical
Operating Temperature	32° to 158° F (0° to 70° C)
Performance	
Sequential Read	7000MB/s*
Sequential Write	6000MB/s*
Random Read	950K IOPS*
Random Write	950K IOPS*

*Actual performance may vary.
NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP M.2 2242 PCIE-4X4 4TB SED Value TLC PCIe SSD

Capacity	4TB
Protocol	PCIe
Form Factor	M.2 in native slot on motherboard
Controller	NVMe
NAND Type	3D TLC
Endurance	2400TBW (TB Written)
Reliability	1.5M Hours
Interface	PCI Express 4.0 x4 electrical
Operating Temperature	32° to 158° F (0° to 70° C)
Performance	
Sequential Read	7000MB/s*
Sequential Write	6000MB/s*
Random Read	950K IOPS*
Random Write	1400K IOPS*

*Actual performance may vary.
NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Technical Specifications - Networking and Communications

NETWORKING / COMMUNICATION (Onboard)

Realtek RTL8127-CG (Integrated)	**Connector**	RJ-45 (Single Port)
	Cabling	Twisted Pair Cabling, up to 100 meter, 10GbE on CAT6 or CAT6a, 5GbE & 2.5GbE on CAT 5e UTP and up, 1GbE/10Mbps on CAT 5 UTP and up
	Controller	Realtek RTL8127-CG 10GbE LAN networking controller
	Data Rates Supported	10/100/1000 M/2.5G/5G/10Gbps
	Compliance	802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.1ad, 802.3az, 802.3x, 802.3bz
	Bus Architecture	PCI Express
	Boot ROM Support	Yes
	Network Transfer Mode	Full-duplex; Half-duplex
	Network Transfer Rate	10G BASE-T Full-Duplex 5G BASE-T Full-Duplex 2.5G BASE-T Full-Duplex 1000BASE-T Full-Duplex 100BASE-TX Full-Duplex 100BASE-TX Half-Duplex 10BASE-T Full-Duplex 10BASE-T Half-Duplex
	Management Capabilities	WOL, PXE, UEFI,
NVIDIA ConnectX-7 (Integrated)	**Connector**	2x QSFP112 form factor
	Cabling	QSFP112 400G DAC Cable, 400mm, 30AWG
	Controller	NVIDIA CX07-V000S4N04C 200GbE networking controller
	Data Rates Supported	Ethernet 200Gbps per port.
	Compliance	802.3ck
	Bus Architecture	PCI Express
	Boot ROM Support	Yes
	Network Transfer Mode	Full-duplex; Half-duplex
	Network Transfer Rate	200Gbps

Technical Specifications - Networking and Communications

AzureWave AW-EM637 IEEE 802.11 a/b/g/n/ac/ax/be Wireless LAN 2T2R and Bluetooth 5.4 Combo Module (Integrated)	**WLAN Standards**	IEEE 802.11 a/b/g/n/ac/ax/be compliant Support 20/40 MHz bandwidth in 2.4 GHz band Support 20/40/80/160 MHz bandwidth in 5 GHz band and 6 GHz band Support MU-MIMO RX IEEE 802.11 d/e/h/i/k/mc/r/v/w support Security support for WFA WPA/WPA2/WPA3 personal/enterprise, WPS2.0, FIPS QoS support of WFA WMM, WMM PS
	Antenna	2x2 Dual-Band
	Bluetooth Standards	5.4

Change log

CHANGE LOG

Date of change	Version History		Description of change
October 27, 2025	From v1 to v2	Changed	Changed notes for Power Adapter and Integrated Graphics, part number for power adapter option kit, list of Input/Output adapters, link to ZGX Toolkit installation web page, Energy Consumption, Heat Dissipation, and Declared Noise Emissions data, Front Power LED to Physical Security and Serviceability section, HP Support site recommendation language to Warranty section, details for WLAN/Bluetooth module in Technical Specifications - Networking and Communications section
February 6, 2026	From v2 to v3	Update	General update and formatting
February 25, 2026	From v3 to v4	Update	HP ZGX 0.4m QSFP112 Ethernet DAC Cable updated to option kit part number and this one added
April 2, 2026	From v4 to v5	Addition	“16MB L2 Cache” added to Processors specs and “Product is TAA Compliant.” added to Warranty note.
November 10. 2026	From v5 to v6	Addition	64GB LPDDR5x memory added
	From v6 to v7		
	From v7 to v8		
	From v8 to v9		
	From v9 to v10		

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